

PRELIMINARY AGENDA

The Next Phase in Engineering Modelling & Simulation

Friday 20 November 2026

Novotel Singapore On Stevens, 28 Stevens Road, Singapore 257878

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Single track – all sessions in the main conference room

08:30	Registration
Session 1	09:00 – 10:20
09:00	Welcome and Introduction David Quinn, NAFEMS
09:20	Mechanistic Origin of Cohesive Bridge Formation in Starve-Fed Twin-Screw Extruder Swan Htet, CSIRO
09:40	Practical Implementation and Use of Model Verification, Validation and Uncertainty Quantification (VVUQ) in Compliance Majji Rao, UL India Pvt. Ltd.
10:00	AI-Augmented Shape Optimization of Monocoiler Designs for Improved Aerodynamic Performance Chian Yeen Fan, Singapore University of Technology and Design
10:20	Break
Session 2	10:50 – 12:10
10:50	Fast Optimization for Vehicle Exterior CFD Performance Using an AI Model Arul Ganesan, Detroit Engineered Products
11:10	A CFD-Acoustic Workflow for Flow-Induced Audible Noise Prediction in a Throttle Control Valve Akash Gupta, Oceaneering
11:30	Evaluating Machine Learning Models for Inverse CFD Problems Fayiz Rahman, NING Research Pte Ltd
11:50	A CFD Study of Dynamic Air Flow Control on Clean Room Particle Concentration Response Kah Xin Khoo, MyCAE Technologies Sdn Bdn
12:10	Photo, Lunch and Exhibition
Session 3	13:30 – 15:10
13:30	PANEL Panel Session: The Role of CAE in an AI World <i>Panellists to be confirmed</i>
14:10	Design-Stage Defeaturing Cost Estimation in Nuclear Engineering Raska Soemantoro, The University Of Manchester
14:30	Failure Investigation of an Aluminium Traverse Bar Using Nonlinear FEA and Field Evidence Hamed Farahpour, Mars Engineers
14:50	Accelerating Automotive Structural Design Exploration via Deep Latent Manifold Learning Bhavaneesh Athikary, Detroit Engineered Products (DEP)
15:10	Break
Session 4	15:40 – 17:20
15:40	Blast-Induced Masonry Fragmentation and Debris Projection Tan Long Bin, A*STAR
16:00	Conversational Agentic Orchestration for CAE Workflows with Traceable Project Context Vijay Nath Sivaraj, Code Product Solutions
16:20	Multiscale Modelling Framework for Wafer-to-Wafer Direct Bonding in Advanced Semiconductor Packaging Nopasorn Kowathanakul, Synopsys
16:40	Overcoming Data Centre Cooling Challenges in an AI World with Physics Based Simulation and AI/ML David Byrne, PD Simulation Pte Ltd
17:00	Industrial Digital Twins <i>Presenter to be confirmed</i>
17:20	Discussion, Awards, Prizes
17:40 – 19:00	Refreshments and Post Conference Networking

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